Intel® Compute Module MFS5520VIR

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Specifications

🔵 Essentials

Status	End of Life
Launch Date	Q2'09
Expected Discontinuance	Q1'13
EOL Announce	Sunday, March 31, 2013
Last Order	Friday, November 01, 2013
Last Receipt Attributes	Sunday, March 30, 2014
Limited 3-year Warranty	Yes
Extended Warranty Available for Purchase (Select Countries)	Yes
# of QPI Links	2
Compatible Product Series	39565, 47915
Board Form Factor	1U
Chassis Form Factor	Rack or Pedestal
Socket	LGA1366
Integrated BMC with IPMI	IPMI 2.0
TDP	95 W
Included Items	(1) Intel Compute Module based on the Intel® 5520 Chipset I/O Hub (IOH) and the Intel® 82801JR ICH10 RAID (Note: Requires installation in a system chassis at UFU V10.3 or V6.6 or higher to operate correctly)
Recommended Customer Price	N/A
Datasheet	Link
Board Chipset	Intel® 5520 Chipset (Intel® 5520 I/O Hub)
Description	Intel Compute Module based on the Intel® 5520 Chipset I/O Hub (IOH) and the Intel® 82801JR ICH10 RAID (Note: Requires installation in a system chassis at UFU V10.3 or V6.6 or higher to operate correctly)
Target Market	Small and Medium Business
Additional Information URL	Link

🔵 Memory Specifications

Max Memory Size (dependent on memory type)	192 GB
Memory Types	DDR3 ECC UDIMM, RDIMM
Max # of Memory Channels	3
Max Memory Bandwidth	1066 GB/s
Max # of DIMMs	12
ECC Memory Supported ‡	Yes

🔵 Graphics Specifications

Integrated Graphics ‡	Yes
Graphics Output	Front Panel 15-Pin

🔵 I/O Specifications

USB Revision	USB 2.0
# of USB Ports	4
RAID Configuration	0, 1, 1E, 5, 6, 10, 50, 60
# of LAN Ports	2
Integrated LAN	Intel® 82575EB Gigabit Ethernet Controller

🔵 Package Specifications

Max CPU Configuration	2
Low Halogen Options Available	See MDDS

🔵 Advanced Technologies

Intel® Virtualization Technology for Directed I/O (VT-d) ‡	Yes

🔵 Intel® Data Protection Technology

AES New Instructions	Yes

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Refer to Datasheet for formal definitions of product properties and features.

"Announced" SKUs are not yet available. Please refer to the Launch Date for market availability.

Some products can support AES New Instructions with a Processor Configuration update, in particular, i7-2630QM/i7-2635QM, i7-2670QM/i7-2675QM, i5-2430M/i5-2435M, i5-2410M/i5-2415M. Please contact OEM for the BIOS that includes the latest Processor configuration update.

‡ This feature may not be available on all computing systems. Please check with the system vendor to determine if your system delivers this feature, or reference the system specifications (motherboard, processor, chipset, power supply, HDD, graphics controller, memory, BIOS, drivers, virtual machine monitor—VMM, platform software, and/or operating system) for feature compatibility. Functionality, performance, and other benefits of this feature may vary depending on system configuration.

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System and Maximum TDP is based on worst case scenarios. Actual TDP may be lower if not all I/Os for chipsets are used.

Low Halogen: Applies only to brominated and chlorinated flame retardants (BFRs/CFRs) and PVC in the final product. Intel components as well as purchased components on the finished assembly meet JS-709 requirements, and the PCB / substrate meet IEC 61249-2-21 requirements. The replacement of halogenated flame retardants and/or PVC may not be better for the environment.

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